

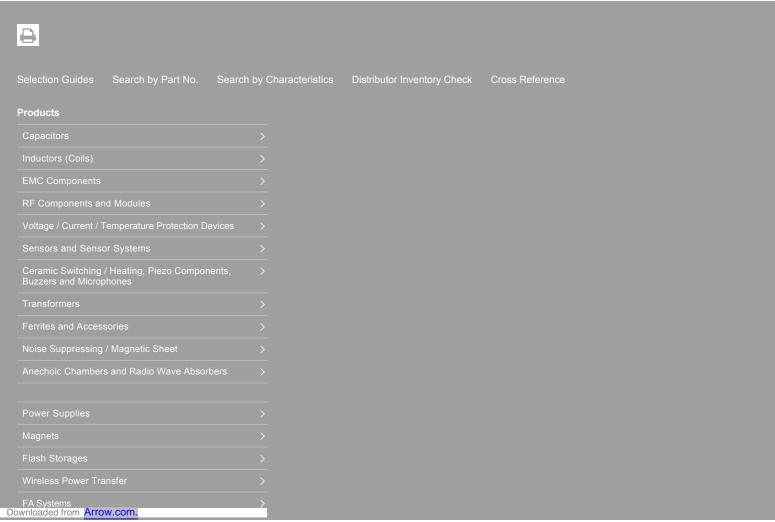
ightarrow Pre ightarrow Inc ightarrow Inductors (Coils) ightarrow Detailed Information

Inductors (Coils)

Product Top Pa	ge Search by Part No.	Search by Characteristics	Cross Reference	Catalog	Tech Notes	▼ more
MHQ04	02P4N0BT	000				RoHS SVHC-Free Halogen Let
Applications	Commercial Gra	de				PDF file of this page
Feature	Non-Mag Core Non-Ma	Mag Core Non-Magnetic Core (Dielectric Ceramic)		0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		Contact
Series Type	Type MHQ-P					Documents
Status	Production (Not Recommended for New Design) Recommended Alternate Part No. : <u>MHQ0402PSA4N0BT000</u> (Interc hangeability is not guaranteed.)) and	Images are for reference only and show exemplary products.		Catalog RoHS Certificate SVHC/REACH Certificate
Brand	трк					Product Lineup
						[Selection Guide] Inductors for high frequency applications Update
Size						Sample Kits
Length(L)		0.44mm ±0.0)2mm			Technical Support Tools
Width(W)			0.24mm ±0.02mm			S-parameter
Thickness Hei	iaht	0.24mm ±0.0				SPICE Netlist (Simple)
•	<u> </u>		0.15mm to 0.20mm			SPICE Netlist (Precision)
Recommended Land Pattern (A) Recommended Land Pattern (B)		0.20mm Non				Equivalent Circuit Model
Recommended Land Pattern (C)			0.18mm to 0.20mm			
Electrical Cha	racteristics					
Inductance		4nH ±0.1nH	4nH ±0.1nH at 500MHz			
Rated Current		200mA	200mA			
DC Resistance [Typ.]		260mΩ				
DC Resistance	[Max.]	500mΩ				
Self Resonant I	Frequency [Min.]	5GHz	5GHz			
Self Resonant F	Frequency [Typ.]	6.7GHz	6.7GHz			
Q [Min.]		10 at 500MH	10 at 500MHz			
Q [Тур.]		13 at 500MH	13 at 500MHz			
Other						
Operating Temp	o. Range (Including Self-T	emp. Rise) -55 to 125°C				
Soldering Method Reflow						
AEC-Q200	•					
Packing Punched (Paper)Taping [180r			per)Taping [180mm	Reel]		
Package Quantity 20000p						
Weight		0.00011a	0.00011g			

characteristics.)

MHQ0402P4N0BT000	MHQ0402P4N0BT000			
Change settings	Change settings			
Inductance	Q			
MHQ0402P4N0BT000	MHQ0402P4N0BT000			
Change settings	Change settings			



Transparent Conductive Film	>	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)		
Solar Cells		
Biosensor		
Application Specific IC (ASIC) Development and Supply		
Application Guides		
Technical Support		
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